ABSTRACT OF THE DISCLOSURE

An electro-optic semiconductor package and fabrication method provides enhanced performance. An integrated circuit (IC) having one or more IC contact pads is provided, where the IC contact pads are connected to an IC on the IC wafer. An intermediate wafer having one or more intermediate contact pads is provided, where the intermediate contact pads are connected to an electro-optic arrangement on the intermediate wafer. The method further provides for direct copper bonding the IC contact pads to adjacent intermediate contact pads such that an electro-optic semiconductor package results.

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